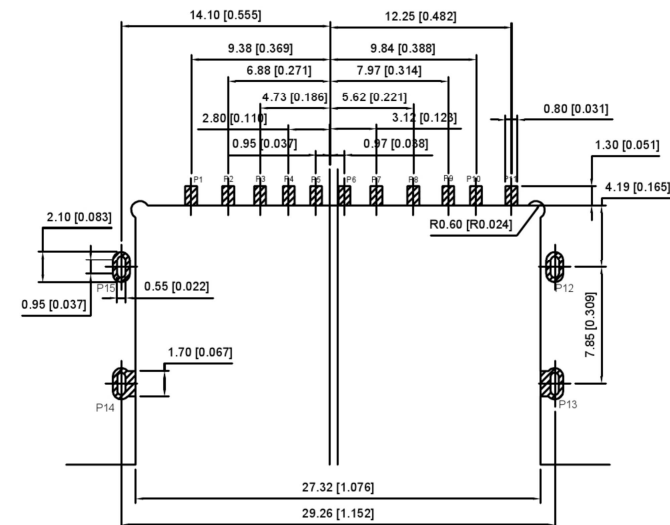
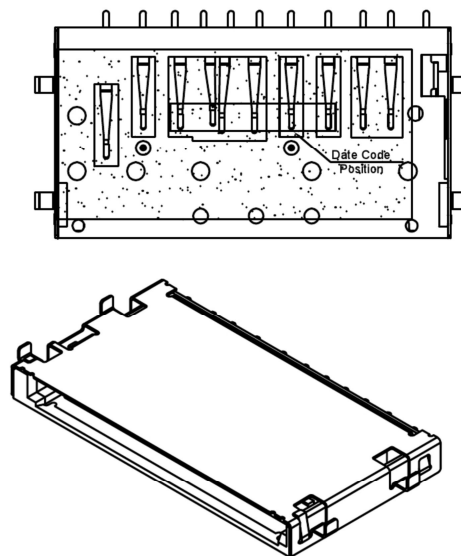
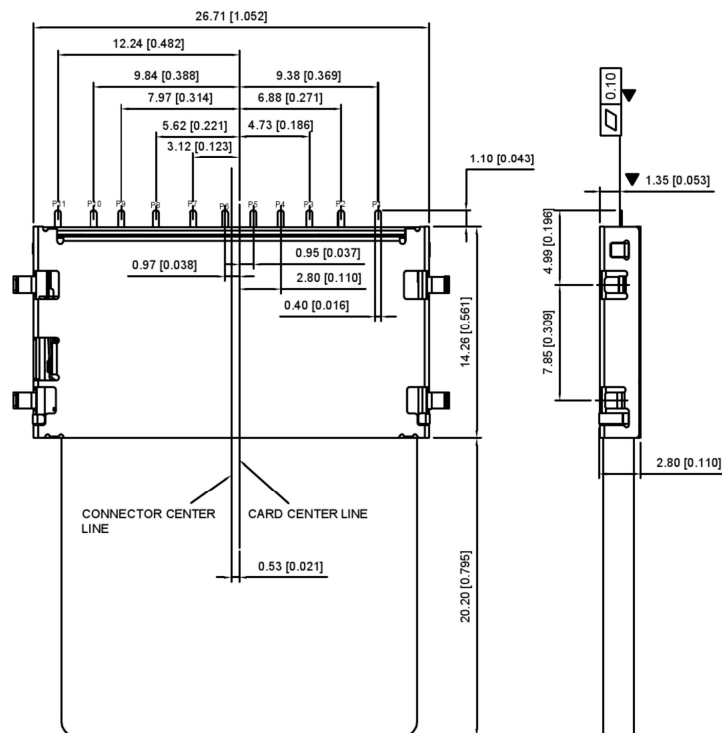




RECOMMEND P.C.B LAYOUT
TOLERANCE ± 0.05

PAD
 No trace , no test point,
no via hole, no ground area

XKB Connectivity

WITHOUT CARD		CARD INSERTED:LOCK		CARD INSERTED:UNLOCK	
W/P	GND	W/P	GND	W/P	GND
C/D	VSS1	C/D	VSS1	C/D	VSS1

Pin Define

Connector Pin NO.	SD Card Pin No.	Pin Define
P1	P9	DAT2
P2	P1	DAT3
P3	P2	CMD
P4		CD
P5	P3	VSS1
P6	P4	VDD
P7	P5	CLK
P8	P6	VSS2
P9	P7	DAT0
P10	P8	DAT1
P11		WP
P12~P15		GND

规格 Specification

*电气特性 Electrical Characteristics:

触点额定电流 Contact Current Rating:0.5 Amperes.
绝缘耐压 Dielectric Withstanding Voltage:AC500V r.m.s.
绝缘电阻 Insulation Resistance:1000 M Ω Minimum.
接触电阻 Contact Resistance:100 m Ω Maximum.

*环境 Environmental:

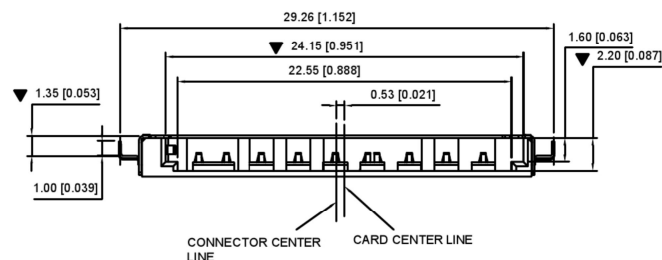
工作温度 Operating Temperature:-25°C~+85°C.

*机械特性 Mechanical Characteristics:

寿命 Mating Cycles:10,000 Cycles Insertion/Extraction
卡推插/拔出力 Card Push Insertion/Out Force:1kgf Maximum.
端子保持力 Contact Retention Force:0.15kgf Minimum.

*材料 Material:

隔热材料 Insulator:HI-Temp Plastic UL 94V-O Rated.
触点 Contact:Copper Alloy.
外壳 Shell:Stainless Steel.



DSND		SCALE: N/A	MODEL TYPE: SIM CARD CONN
DWN		VIEW:	PART NO.: XKSD-1250-1
CHKD		UNIT: mm/in	DWG NO.:
APPD		SIZE: A4	
DONG GUAN XI BANG ELECTRONIC CO., LTD			WEIGHT
			SHEET
			REVISION
			1/1
			A0

				ANGLAR	$\pm 5^\circ$
				$L \leq 4$	± 0.2
				$4 < L \leq 16$	± 0.3
				$16 < L \leq 63$	± 0.4
				$L > 63$	± 0.5
REVISIONS				UNSPECIFIED TOLERANCES	
www.alpsr.com www.gdxjdz.com www.xbswitch.com					

